



KM1712HK-JSW A/B

Technical Data Sheet

PRODUCT DESCRIPTION

KM1712HK-JSW is an epoxy adhesive for electric connection where room temperature cure is required. It has following advantages. KM1712HK-JSW:

- ✧ Electrically conductive
- ✧ High thermal conductive
- ✧ Thixotropic
- ✧ Ease of use
- ✧ Good bond strength

PROPERTIES OF UNCURED MATERIAL

Properties	Test Method	Resin-A	Hardener-B	Mixed-A/B
Color/Appearance	Visual	Silver	Silver	Silver
Specific Gravity, g/cm ³	ASTM D-792	5.2	5.0	5.1
Viscosity @ 25°C, cps	ASTM D-2393	Thixotropic	Thixotropic	Thixotropic

TYPICAL CURED PROPERTIES

Cured 7 days @ 25 °C (77°F)

Property	value
Flexural strength ,psi	10200
Tensile lap shear strength,psi@ 25 °C	1100
Thermal Conductivity , W/M-K	25
Max. service temperature °C	90
Min. service temperature °C	-40
Volume resistivity ohms-cm	0.0006

Thermal Conductivity:Based on Laser Flash

MIX RATIO

Resin/Hardener Ratio (by weight)	100 / 100
Resin/Hardener Ratio (by volume)	100 / 100
Pot Life (100 gram mass), 25°C, minutes	60

CURING TIME TABLE

Temperature	Minimum Cure Time
25 °C (77°F)	16-24 hours
65 °C (149°F)	3 hours
100 °C (212°F)	45 minutes

SHELF METHOD

Store at 25 °C in a dry place. After each use, tightly reseal.

SHELF LIFE

Provided this material is stored under the recommended storage conditions in their original containers, it will remain in useable condition for half year from date of shipping.